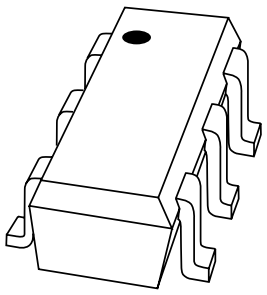
DATA SHEET



PUMZ1
NPN/PNP general purpose transistors

Product specification
Supersedes data of 2002 May 6

2004 Oct 15

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NPN/PNP general purpose transistors PUMZ1

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 40 V)
- Reduces number of components and boardspace.

APPLICATIONS

- General purpose switching and amplification.

DESCRIPTION

Two independently operating NPN/PNP transistors in an SC-88; SOT363 plastic package.

MARKING

TYPE NUMBER	MARKING CODE(1)
PUMZ1	F*Z

Note

1. * = -: Made in Hong Kong.
   * = t: Made in Malaysia.
   * = W: Made in China.

PINNING

PIN	DESCRIPTION	
1, 4	emitter	TR1; TR2
2, 5	base	TR1; TR2
3, 6	collector	TR2; TR1

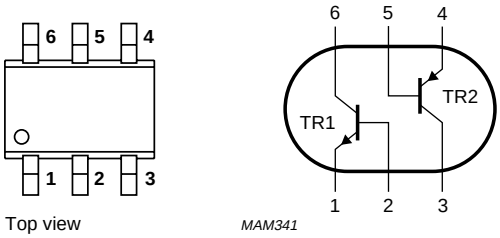


Fig.1 Simplified outline (SC-88) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PUMZ1	–	plastic surface mounted package; 6 leads	SOT363

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transistor; for the PNP transistor with negative polarity					
V_{CBO}	collector-base voltage	open emitter	–	50	V
V_{CEO}	collector-emitter voltage	open base	–	40	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	100	mA
I_{CM}	peak collector current		–	200	mA
I_{BM}	peak base current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	–	200	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C
Per device					
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 1	–	300	mW

Note

1. Device mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
Per device				
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	416	K/W

Note

1. Device mounted on an FR4 printed-circuit board.

CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

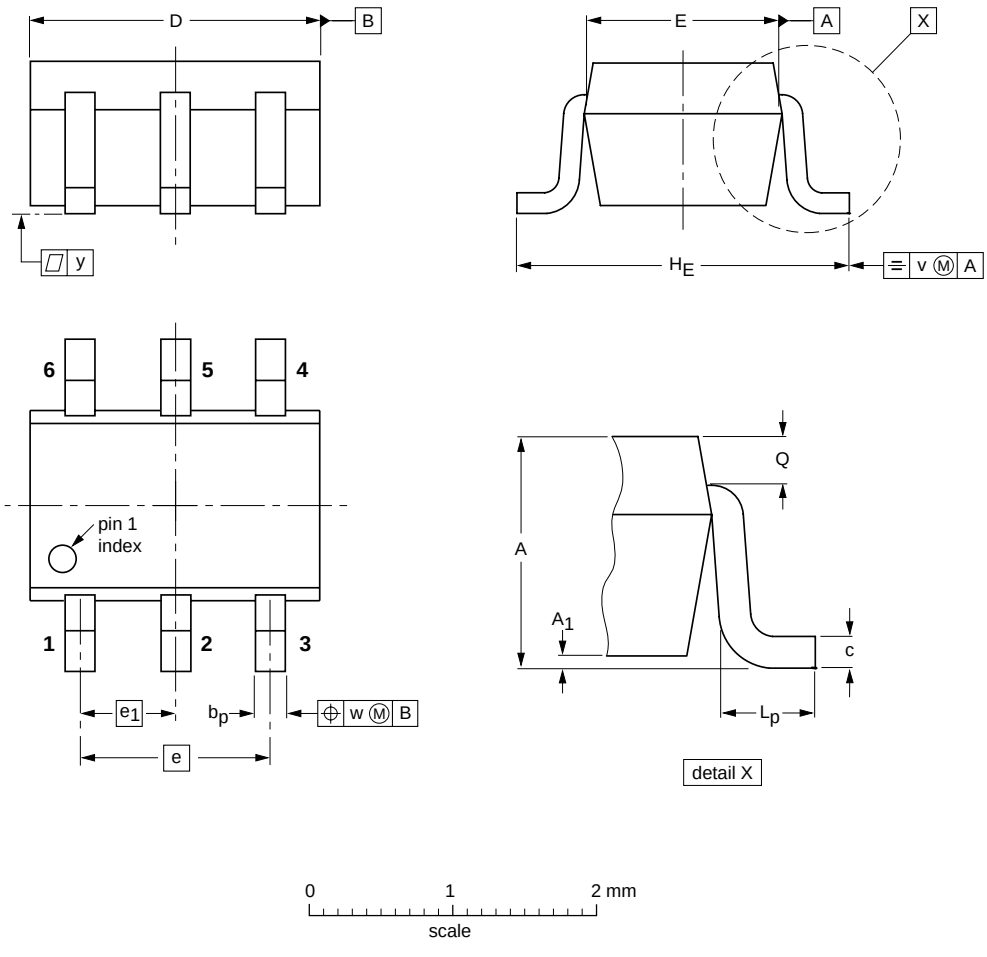
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transistor; for the PNP transistor with negative polarity					
I_{CBO}	collector-base cut-off current	I_E = 0 A; V_{CB} = 30 V	–	100	nA
		I_E = 0 A; V_{CB} = 30 V; T_j = 150 °C	–	10	μA
I_{EBO}	emitter-base cut-off current	I_C = 0 A; V_{EB} = 4 V	–	100	nA
h_{FE}	DC current gain	I_C = 1 mA; V_{CE} = 6 V	120	–	
V_{CEsat}	collector-emitter saturation voltage	I_C = 50 mA; I_B = 5 mA; note 1	–	200	mV
C_c	collector capacitance	$I_E = i_e$ = 0 A; V_{CB} = 12 V; f = 1 MHz			
	TR1		–	1.5	pF
	TR2		–	2.2	pF
f_T	transition frequency	I_C = 2 mA; V_{CE} = 12 V; f = 100 MHz	100	–	MHz

Note

1. Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads **SOT363**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT363			SC-88			97-02-28

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS(1)	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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